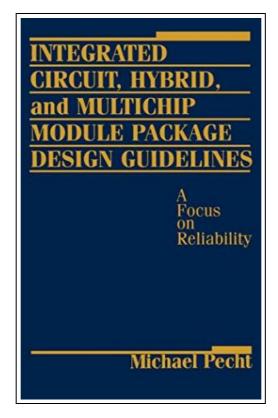
# Integrated Circuit, Hybrid, and Multichip Module Package Design Guidelines: A Focus on Reliability (Hardback)



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# Reviews

This written publication is wonderful. It really is loaded with knowledge and wisdom You will not really feel monotony at at any time of your time (that's what catalogues are for relating to if you ask me).

(Desmond Becker)

# INTEGRATED CIRCUIT, HYBRID, AND MULTICHIP MODULE PACKAGE DESIGN GUIDELINES: A FOCUS ON RELIABILITY (HARDBACK)



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